



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS3104SDR		<b>Issued</b>		24. January 2018			
<b>MA#</b>		MA000546264							
<b>Package</b>		PG-TO252-3-11		<b>Weight*</b>		370.09 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.872	0.51	0.51	5058	5058	
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		175		
	non noble metal	iron	7439-89-6	0.215	0.06		582		
wire	non noble metal	copper	7440-50-8	215.017	58.10	58.18	580981	581738	
	non noble metal	aluminium	7429-90-5	0.516	0.14	0.14	1393	1393	
encapsulation	organic material	carbon black	1333-86-4	1.273	0.34		3440		
	plastics	epoxy resin	-	22.279	6.02		60199		
leadfinish	inorganic material	silicondioxide	60676-86-0	103.758	28.04	34.40	280357	343996	
	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10106	10106	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	245	246	
solder	non noble metal	tin	7440-31-5	0.041	0.01		112		
	noble metal	silver	7440-22-4	0.052	0.01		139		
heatspreader	non noble metal	lead	7439-92-1	1.971	0.53	0.55	5326	5577	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		16		
	non noble metal	iron	7439-89-6	0.019	0.01		52		
	non noble metal	copper	7440-50-8	19.177	5.18	5.19	51818	51886	
*deviation	< 10%				Sum in total:		100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com